

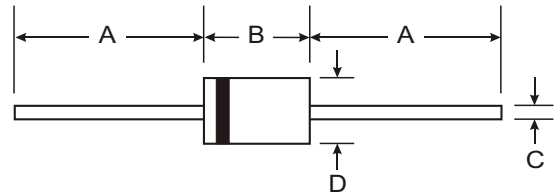
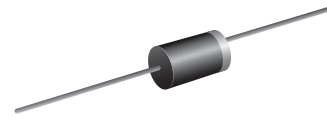
**VOLTAGE RANGE: 100V**  
**CURRENT: 1.0 A**

### Features

- Miniature Size
- Low Forward Voltage drop
- Low Reverse Leakage Current
- High Surge Capability

### Mechanical Data

- Case: D O - 4 1 Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Weight: 0.34 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



DO-41		
Dim	Min	Max
A	25.40	—
B	4.06	5.21
C	0.71	0.864
D	2.00	2.72
All Dimensions in mm		

### Maximum Ratings @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	10EDB10	Unit
Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	100	V
Average Rectified Output Current 50Hz Half Sine Wave Resistive Load	I <sub>O</sub>	T <sub>a</sub> =39 °C *1 1.0 T <sub>a</sub> =26 °C *2 0.9	A
RMS Forward Current Surge Forward Current 50Hz Half Sine Wave, 1cycle, Non-repetitive	I <sub>F(RMS)</sub>	1.57	A
Surge Forward Current	I <sub>FSM</sub>	45	A
Operating Junction Temperature Range	T <sub>jw</sub>	- 40 to + 150	°C
Storage Temperature Range	T <sub>stg</sub>	- 40 to + 150	°C

### Electrical • Thermal Characteristics

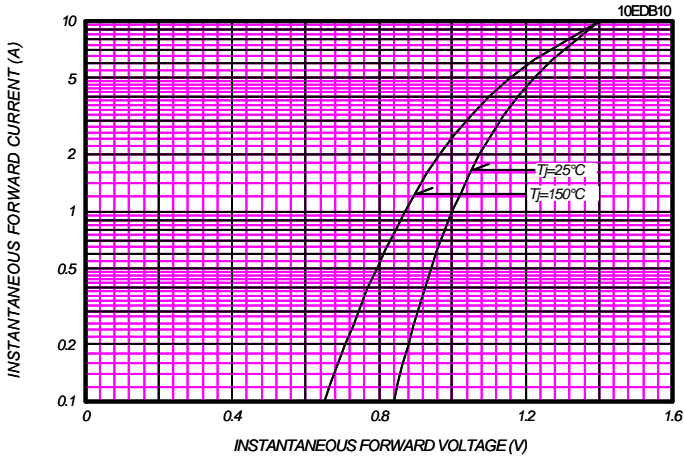
Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit	
Peak Reverse Current	I <sub>RM</sub>	T <sub>j</sub> = 25 °C, V <sub>RM</sub> = V <sub>RRM</sub>	-	-	10	μA	
Peak Forward Voltage	V <sub>FM</sub>	T <sub>j</sub> = 25 °C, I <sub>FM</sub> = 1.0A	-	-	1.0	V	
Thermal Resistance	R <sub>th(j-a)</sub>	Junction to Ambient	P.C. Board mounted*1	-	-	110	°C/W
			Without Fin *2	-	-	140	

\*1: P.C. Board mounted (L=3mm, Print Land=5 x 5mm, Both Sides)

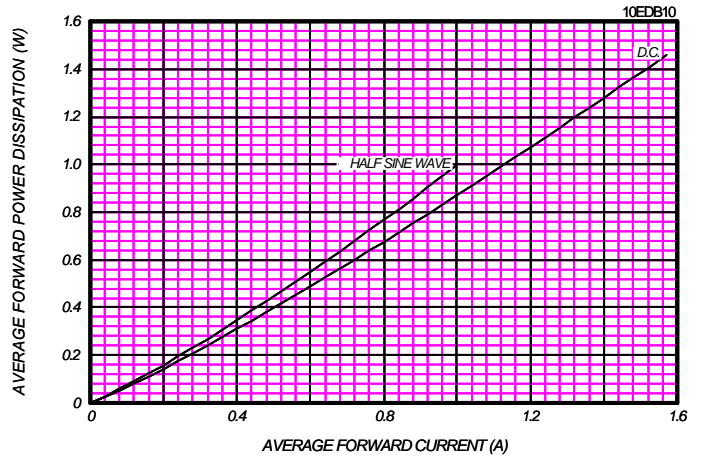
\*2: Without Fin or P.C. Board mounted



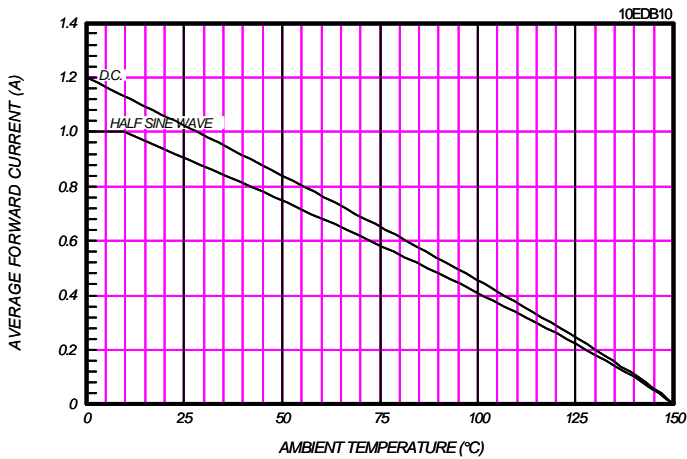
FORWARD CURRENT VS. VOLTAGE



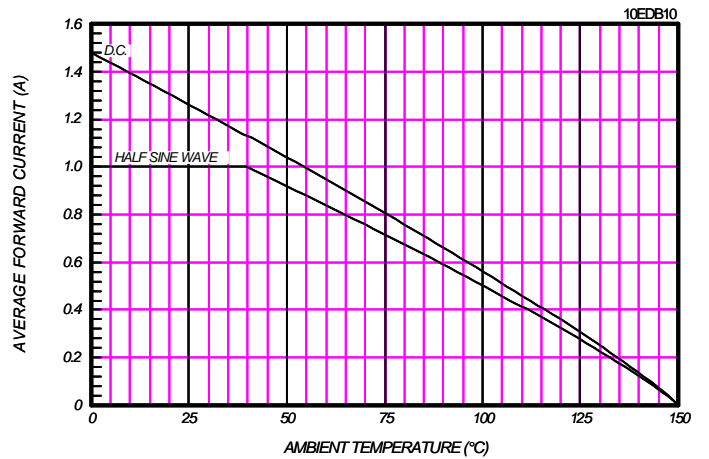
AVERAGE FORWARD POWER DISSIPATION



AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE  
Without Fin or P.C. Board



AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE  
P.C. Board mounted (L=3mm, Print Land=5x5mm, Both Sides)



SURGE CURRENT RATINGS  
f=50Hz, Half Sine Wave, Non-Repetitive, No Load

